



Material Composition Declaration

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This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.

Adobe Reader version 7.0.5 is required to complete this declaration.

1752-2 1.1	IPC Web Site for Information on IPC-1752 Standard http://www.ipc.org/IPC-175x	Form Type * Distribute	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Informat
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Supplier Information

Company Name * Mindspeed Technologies Inc	Company Unique ID N/A	Unique ID Authority N/A	Response Date * 2013-03-22	Response Document ID				
Contact Name * Cynthia Ong	Title - Contact Program Manager	Phone - Contact * 949-579-5515	Email - Contact * cynthia.ong@mindspeed.com					
Authorized Representative * Amy Teng	Title - Representative Quality Engineer	Phone - Representative * 604-6328114	Email - Representative * amy.teng@mindspeed.com	Supplier Comments or URL for Additional Information				
Requester Item Number	Mfr Item Number	Mfr Item Name	Effective Date	Version	Manufacturing Site	Weight *	UOM	Unit Type
M21151G-14	M21151G-14	35FCBGA 1156	2010-10-27	D	ASE, Taiwan	19,242.22	mg	EACH
Alternate Recommendation		NA		Alternate Item Comments	NA			

Manufacturing Process Information

Terminal Plating / Grid Array Material SAC 305	Terminal Base Alloy N/A	J-STD-020 MSL Rating 5	Peak Process Body Temperature 245 C	Max Time at Peak Temperature 40 seconds	Number of Reflow Cycles 3
Comments N/A					

Save the fields in this form to a file

Export Data

Import fields from a file into this form

Import Data

Locked

RoHS Material Composition Declaration

Declaration Type *

Simplified

RoHS Directive 2002/95/EC **RoHS Definition:** Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium

Supplier certifies that it gathered the information it provides in this form concerning RoHS restrictive substances using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substances per the definition above except for selected exemptions

Supplier Acceptance * Accepted

Exemptions: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.

Exemption List Version EL-2006/690/EC

15. Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit Flip Chip packages.

Declaration Signature

Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.

Supplier Digital Signature

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Line Functions: +I Inserts a New Item /SubItem +M Inserts a new Material +C Inserts a new Substance Category +S Inserts a new Substance - Deletes the element line

Item/SubItem Name	Homogeneous Material	Weight	Unit of Measure	Level	Substance Category	Substance	CAS	Exempt	Weight	Unit of Measure	Tolerance		PPM
											-	+	
M21151G-14	Heatslug	5,395.96	mg	C	GROUP-C	Chrome	Trade Secret		2.69798	mg			500
				C	GROUP-C	Copper	7440-50-8		5,360.88	mg			993,49
				B	Nickel/Nickel Compou	Nickel	7440-02-0		32.37576	mg			1,682.5
Ball mount flux	2	mg		C	GROUP-C	Nomionic surfactant	68439-49-6		0.56	mg			279,99
				C	GROUP-C	Bara Terpeneol	8000-41-7		0.66	mg			329,99
				C	GROUP-C	Anime surfactant	61790-85-0		0.78	mg			389,99
Thermally condu	75	mg		C	GROUP-C	Other	Trade Secret		18.375	mg			244,99
				C	GROUP-C	Inorganic Compounds	Trade Secret		33.75	mg			449,99
				C	GROUP-C	Polymer Resin	Trade Secret		20.625	mg			274,99
				C	GROUP-C	Allylether	Trade Secret		2.25	mg			29,999
Substrate	8,850.33	mg		C	GROUP-C	Palladium	67762-90-7		3.75	mg			423.71
				C	GROUP-C	Thallium	Trade Secret		21.66	mg			2,447.3
				C	GROUP-C	Phosphorous	26265-08-7		482.96	mg			54,569
						Calcium oxide	68-12-2		2.74	mg			142.39
				C	GROUP-C	Aluminum oxide	7440-31-5		3.22	mg			363.82
				C	GROUP-C	Zirconium oxide	Trade Secret		219.44	mg			24,794
				C	GROUP-C	Copper	Trade Secret		3.75	mg			423.71
				C	GROUP-C	Strontium oxide	64742-94-5		2.74	mg			309.59
				C	GROUP-C	Gold	Trade Secret		0.68	mg			76.833
						Barium oxide	108-94-1		13.71	mg			712.49
				C	GROUP-C	Chromium oxide	25068-38-6		53.15	mg			6,005.4
				C	GROUP-C	Silicon dioxide	7440-50-8		1,199.02	mg			135,47
				C	GROUP-C	Copper oxide	Trade Secret		5	mg			564.95

				A	Lead/Lead Compound		Boron oxide	7439-92-1		1.89	mg			213.55
				C	GROUP-C		Nickel	65997-17-3		643.95	mg			72,759
Stiffener ring	3,178.73	mg		C	GROUP-C		Chrome	Trade Secret		1.589365	mg			500
				B	Nickel/Nickel Compou		Nickel	7440-02-0		19.07238	mg			991.17
				C	GROUP-C		Copper	7440-50-8		3,158.068	mg			993,49
Die	386.83	mg		C	GROUP-C		Silicon	7440-21-3		386.83	mg			999,99
Flux	1	mg		C	GROUP-C		Distillates, petroleum, st	64741-44-2		0.175	mg			174,99
				C	GROUP-C		Diethanolamine	111-42-2		0.0505	mg			50,499
				C	GROUP-C		Modified rosin	65997-05-9		0.724	mg			723,99
				C	GROUP-C		Triethanolamine	102-71-6		0.0505	mg			50,499
TIM	120	mg		C	GROUP-C		Zinc Oxide	1314-13-2		42	mg			349,99
				C	GROUP-C		Resin	Trade Secret		78	mg			649,99
Underfill	42	mg		C	GROUP-C		Bisphenol A type liquid	25068-38-6		1.26	mg			29,999
				C	GROUP-C		Additives	Trade Secret		0.84	mg			19,999
				C	GROUP-C		Silicon dioxide	60676-86-0		21	mg			499,99
				C	GROUP-C		Organic acid anhydride	Trade Secret		8.4	mg			199,99
				C	GROUP-C		Phenolic resin	9003-35-4		0.84	mg			19,999
				C	GROUP-C		1,6-Bis(2,3-epoxypropox	27610-48-6		8.4	mg			199,99
				C	GROUP-C		Carbon black	1333-86-4		0.42	mg			9,999.9
				C	GROUP-C		Amine type accelerator	Trade Secret		0.84	mg			19,999
Ink	0.5	mg		C	GROUP-C		Phenol	108-92-5		0.015	mg			29,999
				C	GROUP-C		Carbon black	1333-86-4		0.3	mg			599,99
				C	GROUP-C		Formaldehyde	50-00-0		0.065	mg			129,99
				C	GROUP-C		Propylene glycol monom	108-65-6		0.04	mg			79,999
				C	GROUP-C		Isobutyl alcohol	78-83-1		0.015	mg			29,999
				C	GROUP-C		Triethyl phosphate trieth	78-40-0		0.065	mg			129,99
Solder Ball	1,017.78	mg		C	GROUP-C		Cu	7440-50-8		5.0889	mg			5,000
				C	GROUP-C		Sn	7440-31-5		971.9799	mg			954,99
				C	GROUP-C		Ag	7440-22-4		40.7112	mg			40,000
Bump	172.09	mg		C	GROUP-C		Sn	7440-31-5		6.5646	mg			38,146
				A	Lead/Lead Compound		Pb	7439-92-1		165.5254	mg			961,85